Product Change Notification

#113164 – 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**113164-00**
Change Title:	**Intel® Thermal Solution RTS2011AC converting to Intel® Thermal Solution TS13A, PCN 113164-00, Product Material**
Date of Publication:	**July 30, 2014**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	August 29, 2014

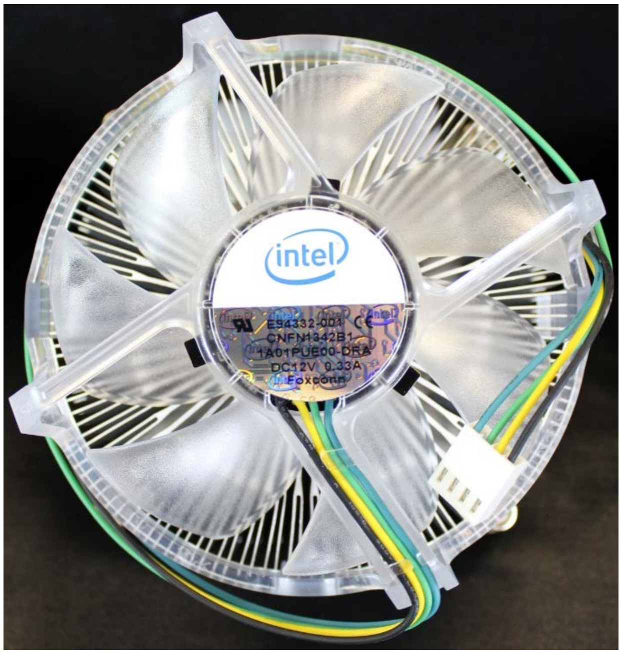
Description of Change to the Customer:

Intel will be launching fan heatsink solution TS13A September 2014 to replace the current fan heatsink solution RTS2011AC.

Customers will see the following four changes for heatsink solution TS13A**:**

1.) New blue label top of the fan

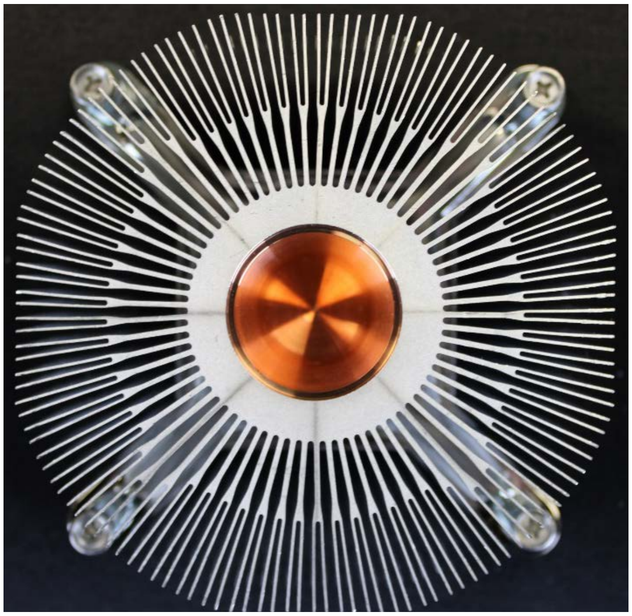
Current RTS2011AC with fan



New TS13A with fan

2.) The copper core has been replaced with a copper heat column

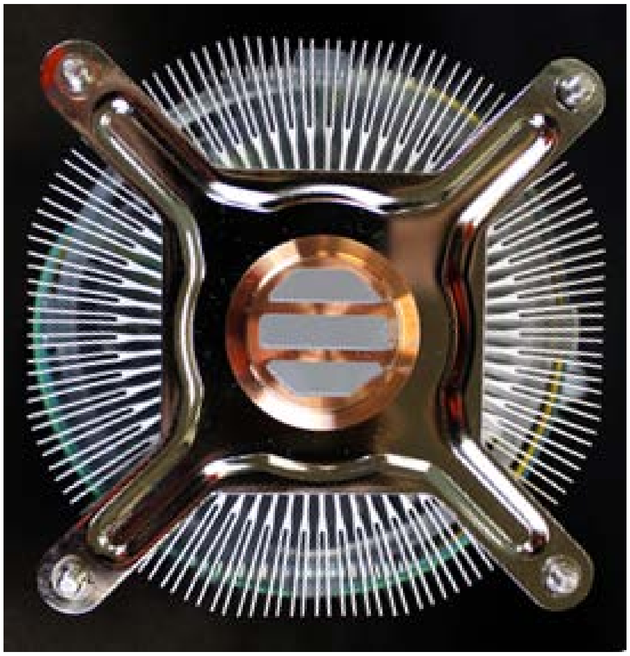
Current RTS2011AC top view w/o fan



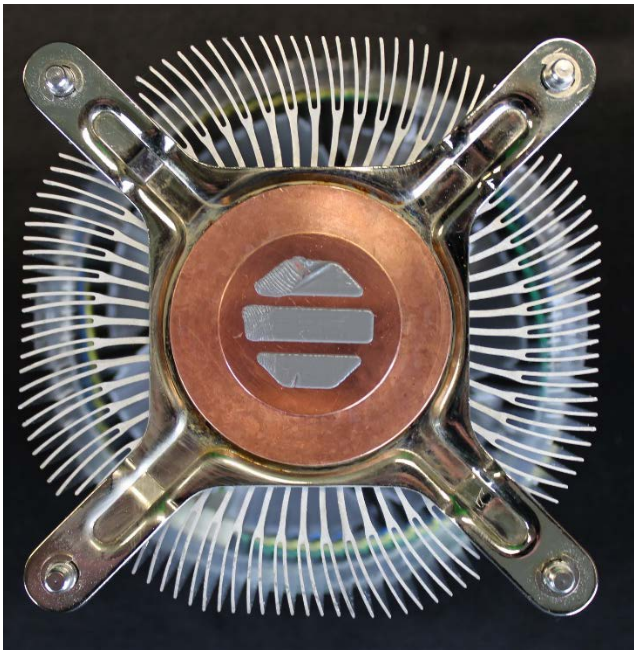
New TS13A top view without fan

3.) The base of the copper heat column has a larger copper base

Current RTS2011AC bottom view



New TS13A bottom view



4.) Heatsink height has incremented from 63mm to 75mm

Current RTS2011AC side view

New TS13A side View

These changes will increase the heatsink performance in order to meet the new processor Thermal Design Point (TDP) requirement of 140W. Customers using the RTS2011AC heatsink will need to switch to the TS13A heatsink as Intel will stop production of the RTS2011AC.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers for this change. Customers will see a mixture of current products and new TS13A heatsink products until all current inventory has been depleted. Customers may want to notify their receiving department of the new product changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Pre Conversion Product Code	Pre Conversion MM#	Post Conversion Product Code	Post Conversion MM#
Intel® Thermal Solution	BXRTS2011AC	918700	BXTS13A	937425

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 30, 2014	00	Originally Published PCN